

MPI Corporation 6223.TT

Presentation Disclaimer

The information herein contains forward-looking statements. We have based these forward-looking statements on our current expectations and projections about future events. Although we believe that these expectations and projections are reasonable, such forward-looking statements are inherently subject to risks, uncertainties and assumptions about us, including, among other things: the intensely competitive Semi-conductor, and LED industries and markets; Cyclical nature of the semiconductor industry; Risks associated with global business activities; General economic and political conditions. All financial figures discussed herein are prepared pursuant to IFRS. All audited figures will be publicly announced upon the completion of our audited process.

MPI Divisions

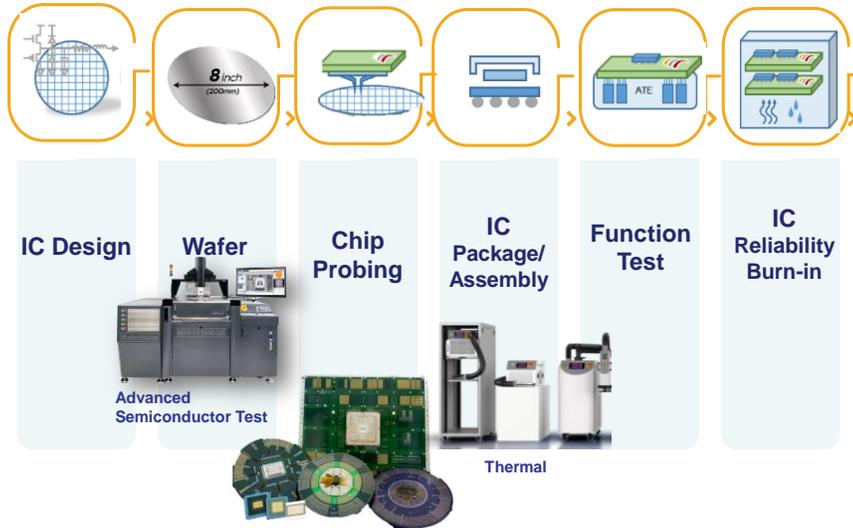


MPI Global Presence



MPI Locations	Worldwide			Taiwan			
 MPI America CA, USA (2017)	 MPI Suzhou Jiangsu, CN (2017)	 Celadon Systems MN, USA (2021)	 Headquarters Hsinchu, TW (2000)	 Luzhu Office Kaohsiung, TW (2006)	 2 nd Production Site Hsinchu, TW (2012)	 Xinyu Office Hsinchu, TW (2014)	 3 rd Production Site Hsinchu, TW (2021)

Supply Chain Infographic



Agenda



Business Contents

- Probe Card
- Photonics Automation
- Thermal & AST



Financial Statements

MPICORPORATION

Probe Card

READY FOR THE TEST™

MPI Probe Card

Advanced Wafer Sort Test Solutions

Vertical / MEMS Probe Card

Cantilever Probe Card



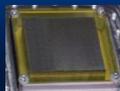
Features



Fine Pitch



MEMS



High Pin Count



High Speed



Substrate



Hand-wired

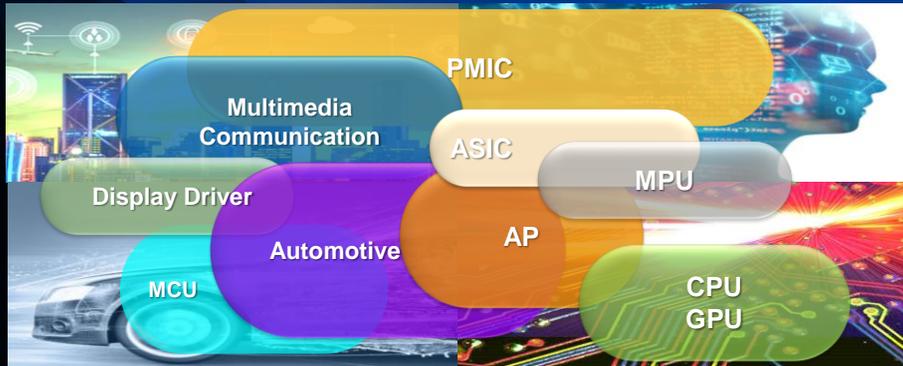


RF

MPI Probe Card

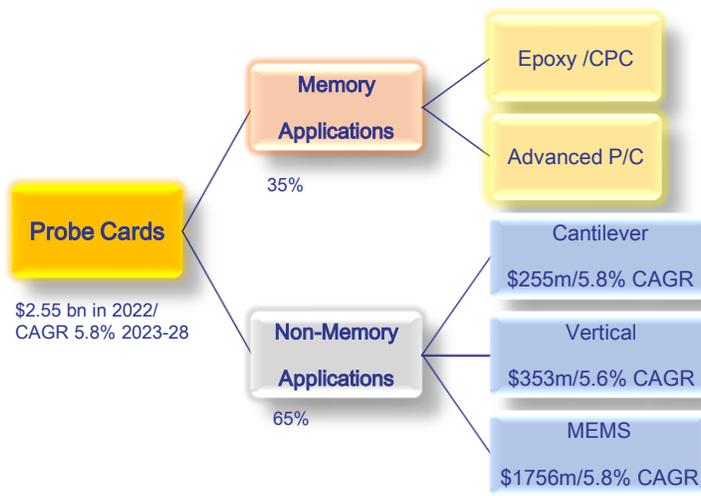
Company Confidential C

Full range of products for the applications
sufficient coverage solutions to IC markets



9

Global Probe Card Market Update

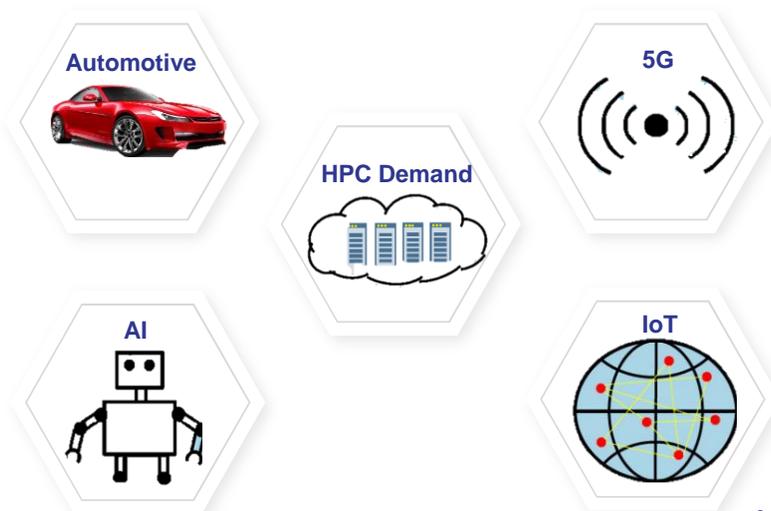


Top 10 Probe Card Vendors (2017-2022)

(Rank)	2017	2018	2019	2020	2021	2022
FormFactor, Inc. (USA)	1	1	1	1	1	1
Micronics Japan Co., Ltd. (Japan)	2	3	3	3	3	3
Technoprobe (Italy)	3	2	2	2	2	2
Japan Electronic Materials (Japan)	4	4	4	4	4	4
MPI Corporation (Taiwan)	5	5	5	5	5	5
SV TCL (Singapore)	6	6	6	7	8	7
Microfriend (Korea)	7	10	10	10	-	-
Korea Instrument (Korea)	8	7	8	6	7	6
Cascade Microtech (USA)	-	-	-	-	-	-
FEINMETALL (Germany)	11	12	11	14	-	-

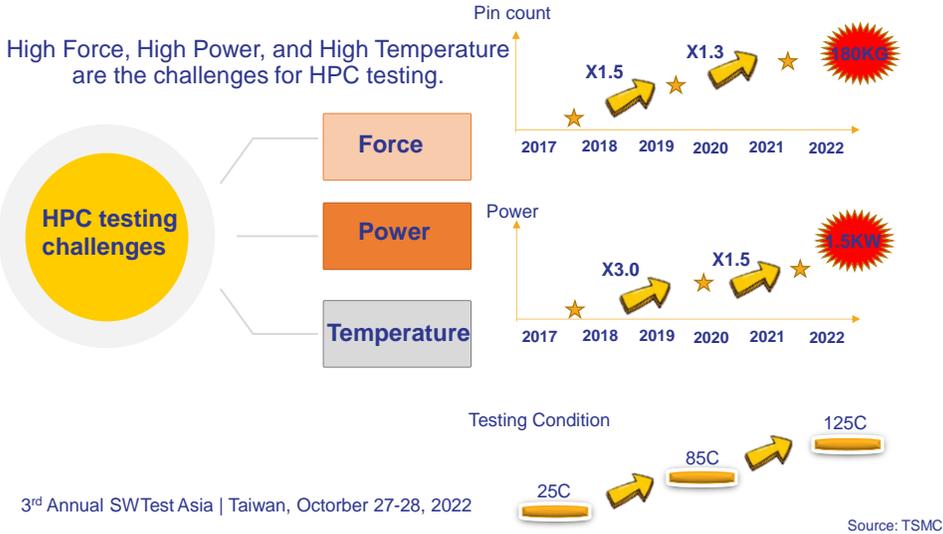
HPC Demand

The demand of HPC (High Performance Computing) growth rapidly.



Source: TSMC

HPC Challenges



Interface Technical Complexity Check in

Complexity Trends are on pace to be at 2022 targets (1 Cycle) or in some cases beyond

“2x4 Scaling”=2xPins, 2xPerformance, every 4 years

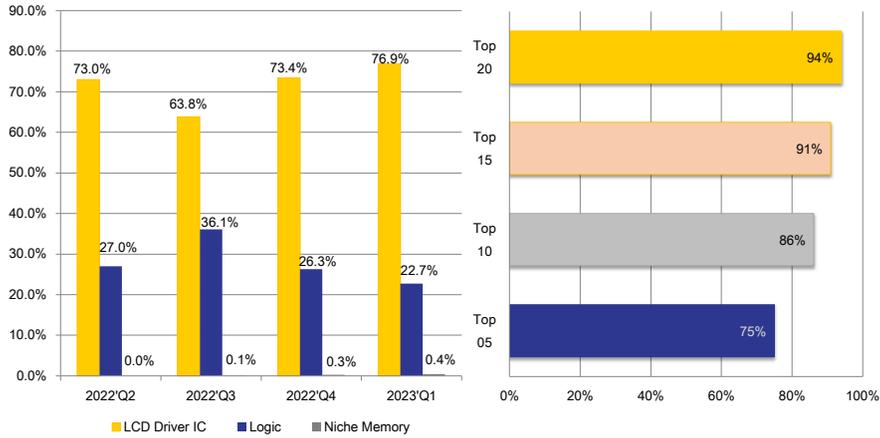


		2018	2022	2026
		Level 4	Level 5	Level 6
Pin Density	Pin Pitch	90um	70um	50um
	Total Contact Force	80kg	150kg	250kg
I/O Speed	Digital	32Gpbs	64Gpbs	128Gpbs
	RF/mmWave	< 12 GHz	29 GHz	+60 GHz
Device Power	Main Power	900 mV	750mV	625mV
	Single Rail	35A	50A	100A
	Impedance	2.2 mOhm	1.4 mOhm	0.8 mOhm
Thermal	Self Heating	75 W		
	Operating Range	0 to +80C	0 to +105C	-20 to +125C
Most Expensive Probe Card		\$400K*	>\$500K	>\$700K

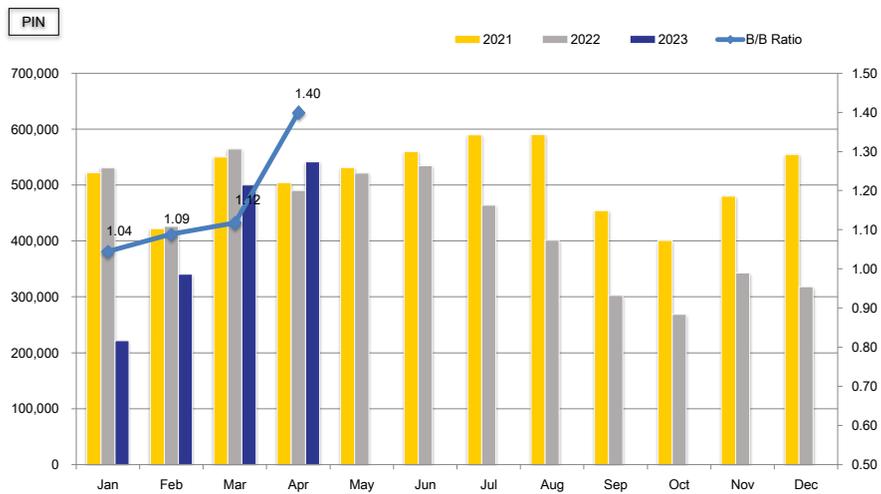
Source:Teradyne

Source:VLSI Research

Product Mix of CPC (Cantilever)



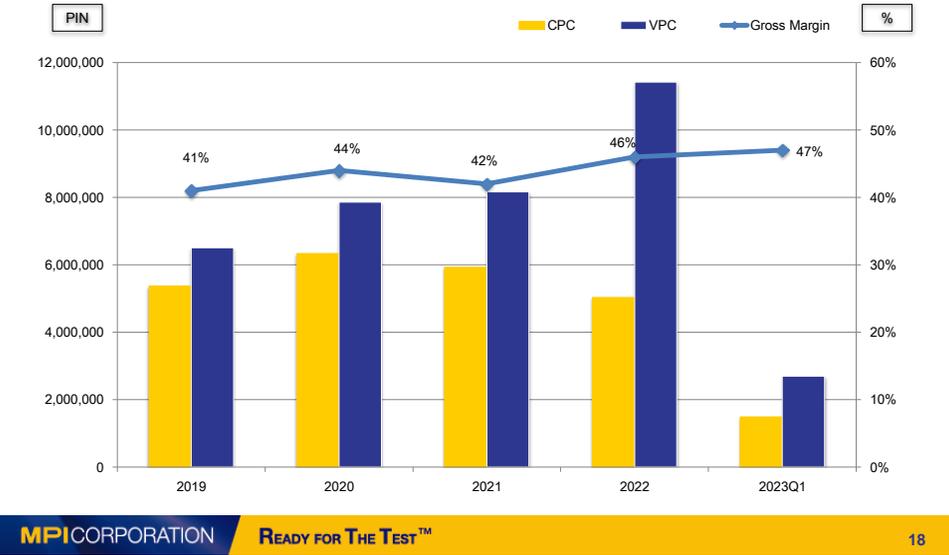
CPC Pin-Shipment_2023



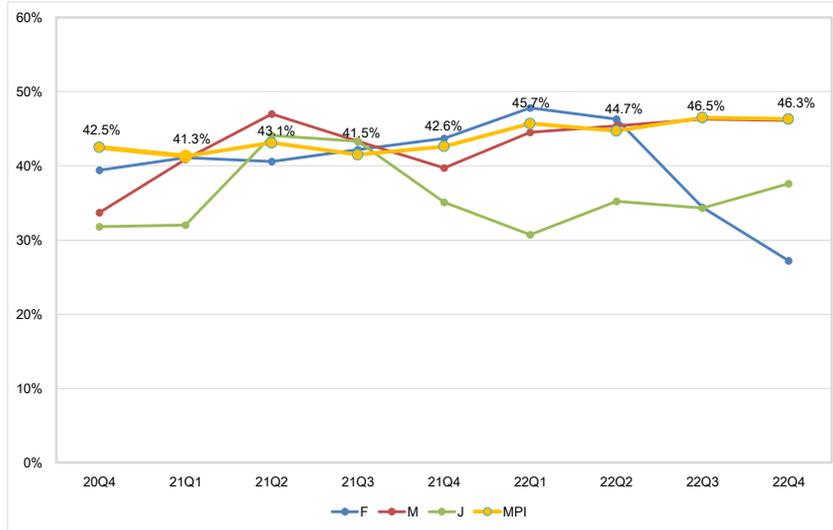
VPC Pin-Shipment_2023



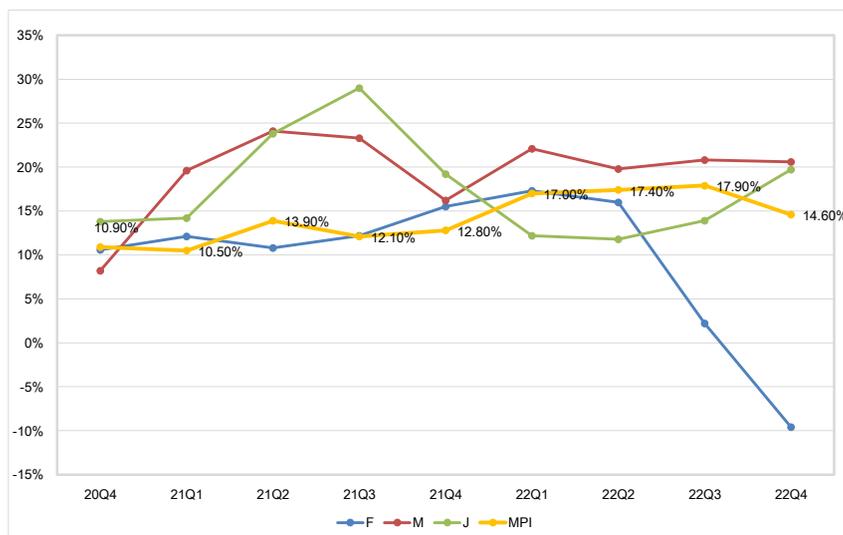
CPC and VPC Yearly Status



Gross Margin Between Global Peers



Operating Margin Between Global Peers



MPI Probe Card

Company Confidential C

Our Customer

The MPI is committing more than 800 customers globally to contribute to industrial development as well as providing testing industry advanced technology needs.



21

MPI CORPORATION

Photonics Automation

READY FOR THE TEST™

Product Portfolio and Capability



- **High Power VCSEL Wafer Testing**
Wafer / Board Prober Development
Testing methodology Development
- **VCSEL / Photo-Detector Testing**
Wafer / Board Prober Development
Testing methodology Development
- **uLED Mass Production Methodology**
Wafer prober for large quantity die testing method
- **High Power VCSEL PKG Testing**
PKG Handler Development
Testing methodology Development
- **RF Character**
Wafer Level RF Testing Integration
- **Panel testing platform development**
Panel / Panel in-process testing platform
- **SiPh Die/PKG Platform**
SiPh Handler Development

Development Plan by Application



Optical Sensing	Optical Communications	Micro Display
<ul style="list-style-type: none"> ➤ Focus on Sensing VCSEL Testing ➤ Production Wafer Prober in Low Temperature ➤ High Power Measurement Tool and Technology Development ➤ Flip Chip Wafer VCSEL testing Solution ➤ Package / Hybrid Device testing tool 	<ul style="list-style-type: none"> ➤ Focus on VCSEL/Photodetector Testing ➤ Wafer Prober for Dark / Responsivity / Capacity measurement ➤ RF Measurement Capability Development ➤ SiPh package testing approaching 	<ul style="list-style-type: none"> ➤ Lab and production wafer testing tool development ➤ Contacting Accuracy Improvement ➤ Innovative testing methodology ➤ Optical measurement in production methodology

MPI CORPORATION

Thermal/AST

READY FOR THE TEST™



MPI Thermal
Hot and Cold Air Flow
Environmental Temperature Test

-100°C  +300°C

ThermalAir Series
Temperature Testing Systems

Applications & Industry Segments

- Semiconductor
- Automotive
- Aerospace
- Telecommunications
- Fiber Optic
- Electronics
- Sensors
- Advanced Technology

The advertisement features a dark blue background with light blue streaks. It displays a variety of MPI Thermal testing equipment, including a small benchtop unit with a test chamber, several larger floor-standing units with air flow nozzles, and a smaller portable unit. The equipment is arranged in a row, showcasing different models and sizes. The text is in white and yellow, providing clear information about the company, product line, and industry applications.

MPI Advanced Semiconductor Test

Engineering Probe Systems
and
RF Probe Products

50 - 300 mm

26 - 110 GHz

Applications & Industry Segments

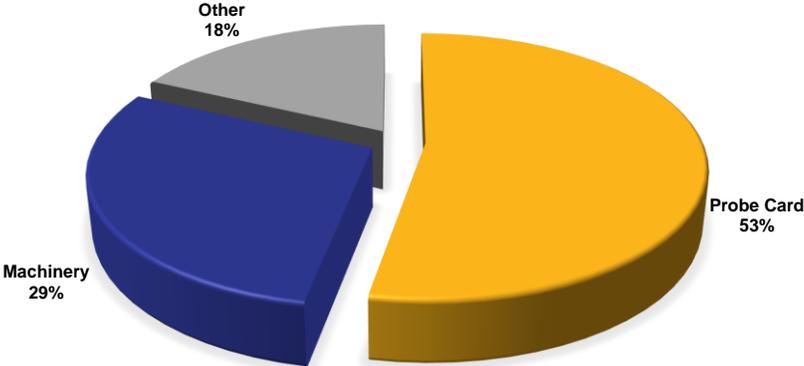
Device Characterization	High Power	RF & mmW	Design Validation	Failure Analysis	Wafer Level Reliability	Silicon Photonics	Laser Cutter

MPI's Ideation

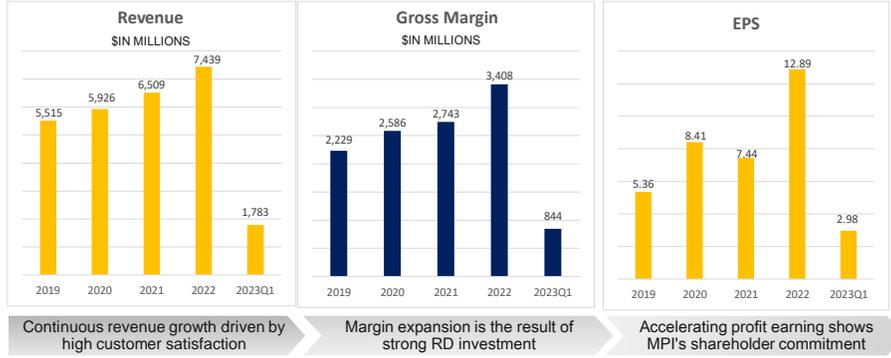
- To Combine Two Very Unique Values
- The MPI Corporation
 - Operational Excellence – High quality, on time
 - Production Test Experience – 24/7 systems reliability
 - Customer Centric – Highest value without compromise
- Management & Market Expertise
 - More than 50 years together in Device Modeling, RF & mmW, WLR, High-Power, Failure Analysis, Thermal solutions...
 - Visionary and Innovative Ideas
 - Worldwide Partner Relationships

Financial Statements

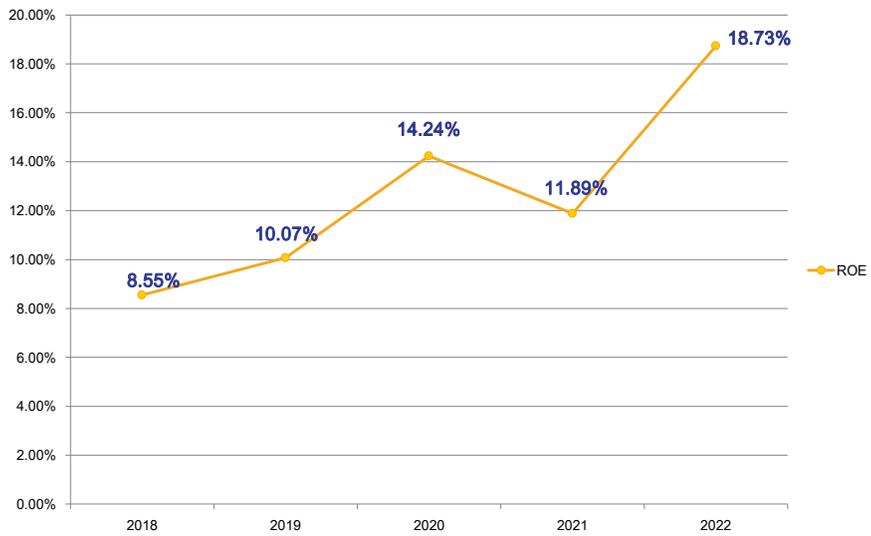
1Q23 Shipment Breakdown



Solid Performance



ROE



Balance Sheet Highlight

NT\$Million	2023' 1Q		2022' 1Q	
Cash and Cash Equivalents	2,385	22%	1,307	13%
Fixed Assets	4,481	41%	4,408	44%
Total Assets	10,959	100%	10,035	100%
LT Debt	996	9%	1,113	11%
Shareholders' Equity	7,204	66%	6,376	64%
EBITDA	333	18%	366	21%

*EBITDA=operating income + depreciation & amortization expenses

Income Statement

NT\$Million	1Q2023		1Q2022	
Net Sales	1,783,537	100%	1,720,155	100%
Cost of Goods Sold	939,346	53%	934,315	54%
Gross Profit	844,191	47%	785,840	46%
Operating Expense	517,648	29%	492,651	29%
Operating Income	326,543	18%	293,189	17%
Investment Income & Others	6,864		73,674	
Net Income (before tax)	279,721	15%	306,230	18%
EPS	2.98		3.25	

MPICORPORATION



Thank You



<http://www.mpi-corporation.com>

READY FOR THE TEST™